

Tradeoffs in Flight-Design Upset Mitigation in State-of-the-Art FPGAs

Hardened By Design vs. Design-Level Hardening

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In the beginning was Actel ...

- Leveraging from a commercial product line
 - ONO anti-fuse based → one-time programmable (OTP)
- “beginning” = 1993
 - Reference:
Katz, R.; Barto, R.; McKerracher, P.; Carkhuff, B.; Koga, R.;
“SEU hardening of field programmable gate arrays (FPGAs) for space applications and device characterization,” *IEEE Transactions on Nuclear Science*, Dec. 1994

Later, Xilinx

Leveraging from a commercial product line

- SRAM based → reconfigurable

“later” = 1998

- Reference: Guertin, S.M.; Swift, G.M.; Nguyen, D.; “Single-event upset test results for the Xilinx XQ1701L PROM”, *Radiation Effects Data Workshop Record*, 1999
- Quote:
(Xilinx SRAM-based FPGAs)... “do appear suited to a broad range of other (non-critical) applications, such as sensor and camera controllers.”

OUTLINE

- FPGAs:
A key enabling technology for modern spacecraft
- Background in radiation testing of FPGAs
 - Earlier, Katz/Swift collaboration
 - Recently, Xilinx Consortium
- Feature Comparison
- Triple Modular Redundancy (TMR) -
hardware approach vs. software approach
- Concluding Remarks

FPGAs: A key “enabling technology”

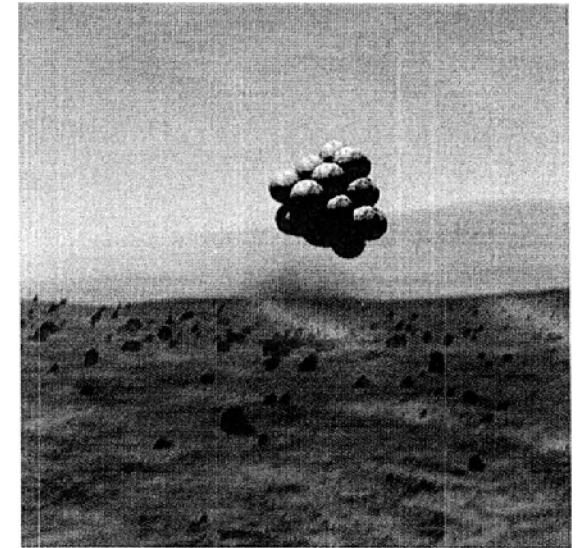
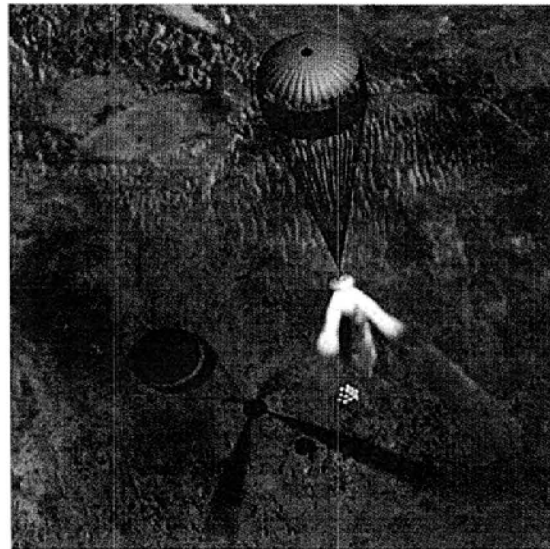
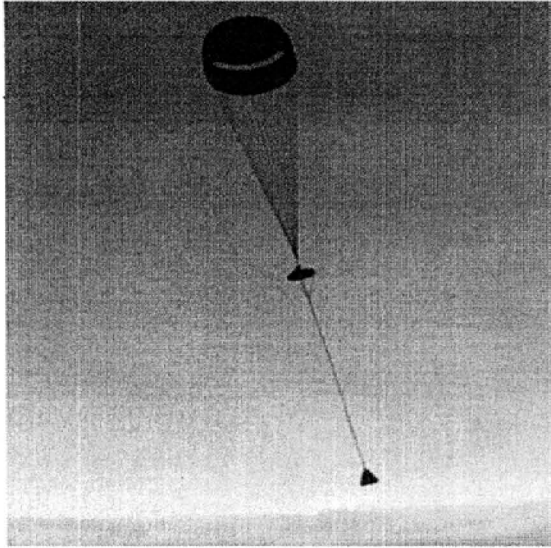
Like custom ASICs, FPGAs can replace whole boards

- Saving mass, volume, power
- Achieving extra functionality

FPGAs are much cheaper than ASICs

- Design efforts can be later in the schedule
- Design mistakes don't require a re-spin through the foundry

MER Pyro-Controller

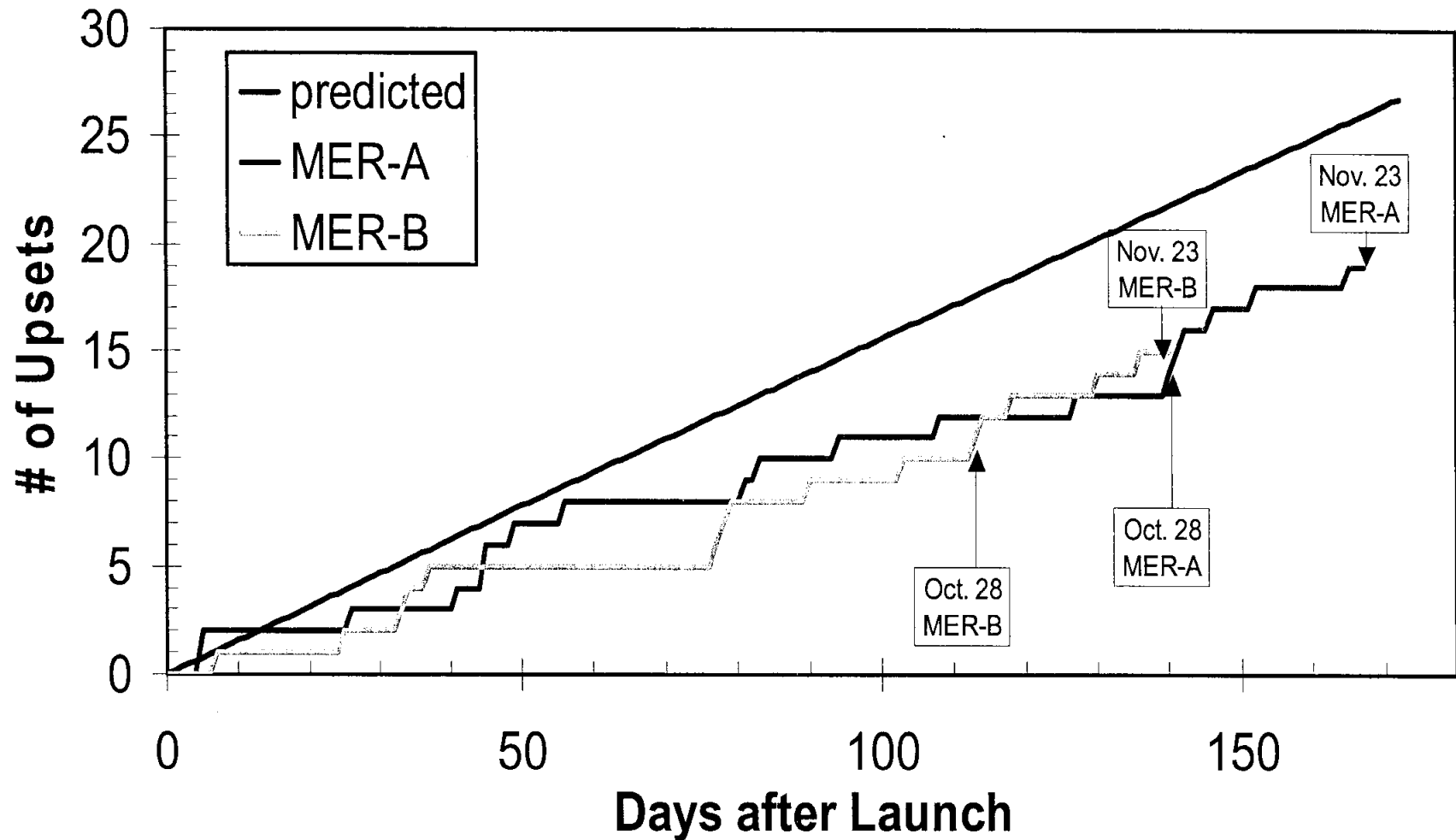


Used self-checking of configuration to initiate a re-configuration after spotting an upset

MER Pyro-Controller

Nearing Mars

Xilinx XQR4062XL



My Background

- Actel has not been directly involved in recent radiation testing
 - No direct involvement in radiation tests since the ONO anti-fuse was replaced
 - Results here are from others' work
- Xilinx experience is recent
 - Active participant in Xilinx Rad Test Consortium
 - Currently, finishing two+ year test campaign targeting the Virtex II family

Comparison of “current” devices

Actel RT54SX-S family vs. Xilinx Virtex II family

Note: both are essentially immune to single-event latchup
and have good total ionizing dose tolerance,
[Actel > 135 krad(Si); Xilinx > 200 krad(Si)]

Main Feature Comparison

	Actel	Xilinx
Pins:	~550	>1000
Gates:	72,000 2012	~6M (/~3.4) 67,584 / 3 = ~22.5k
Speed:	200 MHz	650 MHz

Extra Features Comparison

	Actel	Xilinx
BRAM:	no	2Mb
I/O Standards:	many	many
Others:	hardwired TMR	Clock Manager Multipliers

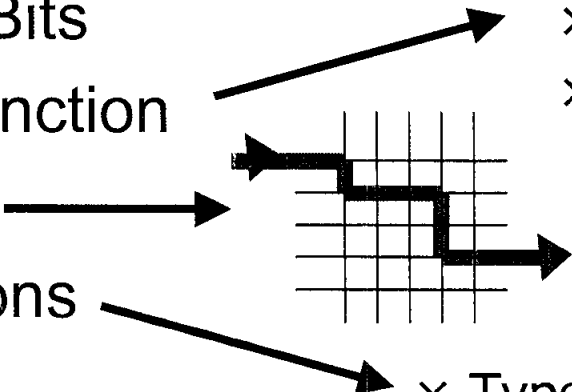
Actel: What bits can upset?

User flip-flops only

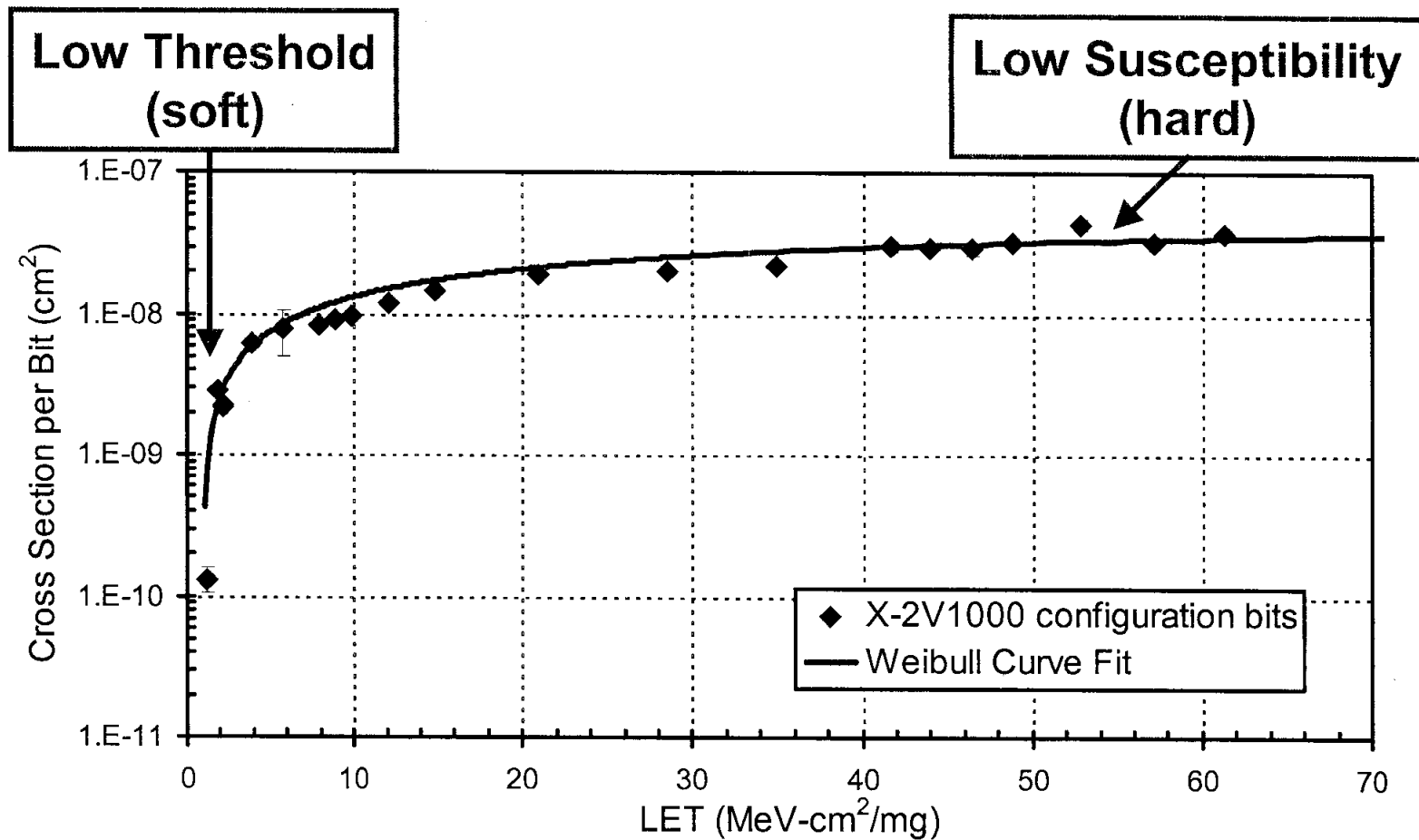
- Direct hits of same flip/flop in multiple domains
 - Very unlikely due to layout
- Clock domain hits

SEFI modes essentially eliminated

Xilinx: What bits can upset?

- Configuration Bits
 - Logical Function
 - × NAND
 - × Ex-OR
 - × Flip-Flop type
 - × etc...
 - Routing
 - × Type of I/O
 - × Mode of BRAM Access
 - × Clock Manager
 - × etc...
 - User Options
 - BRAM
 - User Flip-flops
 - Control Registers
- 
- A diagram showing a routing grid with a path of thick black lines. Three arrows point from the text 'Logical Function', 'Routing', and 'User Options' to the grid. The 'Routing' arrow points to the path itself. The 'Logical Function' arrow points to the top-right area of the grid. The 'User Options' arrow points to the bottom-right area of the grid.

Xilinx: In-beam Test Results



Resulting in fairly low in-space rates

e.g., rate for 2V1000 in GCR_{min} is 1 per day.

Actel-style TMR

Actel-style TMR is straightforward:

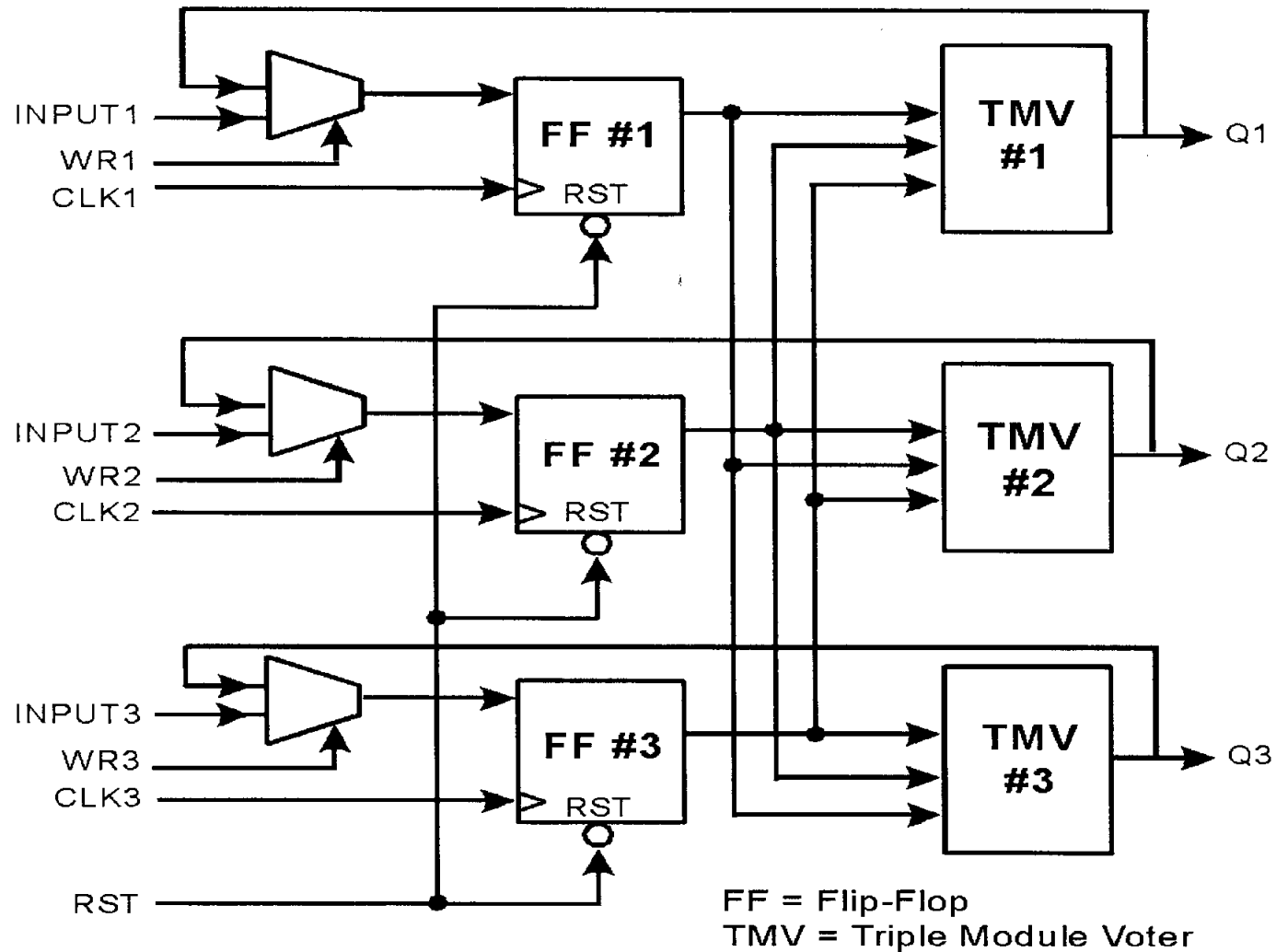
- Each flip-flop is replaced by three plus a voter
- Uses one clock domain
- No external parts

Xilinx-style TMR

Xilinx-style TMR is more complicated:

- First, it's not too useful without configuration scrubbing
- Whole functional blocks are triplicated, *not* individual flip-flops,
- Three voters are used
- Three clock domains
- Elimination of:
 - Weak keepers (aka half latches)
 - Use of configuration cells as part of the design
 - For example, SRL16
- Needs some external circuitry
(at least, a watchdog timer)

Xilinx-style TMR



Xilinx TMRtool

- Xilinx-style TMR done by hand is difficult and tedious
- An automated tool which integrates into the design flow has been developed (“now” available)
- In-beam testing shows tools is very effective

Upset Comparison

- ATMR now has eliminated:
 - Upsets of static storage elements, and
 - SEFIs
- ATMR upsets from:
 - Transients that are clocked into storage
 - Clock tree hits
- Xilinx FPGAs have a small susceptibility to two types of SEFIs
 - Reset (sometimes only partial)
 - Disable scrub port
- XTMR in combination with scrubbing can lower system upset rates below the SEFI rate

Rate Comparison

- Actel
 - Dominated by transients
 - Roughly a system error per few thousand years (GCR)
- Xilinx
 - Dominated by SEFI rate
 - Expect one in 65 years in GCR

GCR = **G**alactic **C**osmic **R**ay background (interplanetary space)
almost identical to geosynchronous orbit

CONCLUSIONS

For the present –

Both can achieve very acceptable radiation tolerance

Actel wins on:

- Less burden on the designer
- No auxiliary components
- Lower SEFI susceptibility

Xilinx wins on:

- Designer control of the resources vs. hardness tradeoff
- On-chip feature set
- Re-configurability

Competition is good.

Acronyms

FPGA - Field Programmable Gate Array

ASIC - Application Specific Integrated Circuit

SEU - Single Event Upset

SEFI - Single Event Functionality Interrupt

TMR - Triple Modular Redundancy

ATMR - Actel-style TMR

XTMR - Xilinx-style TMR

A.U. - Astronomical Unit (earth-sun distance)

MER - Mars Exploration Rovers

(i.e., Spirit and Opportunity)

Additional References

- [1] Katz, R.; Wang, J.; McCollum, J.; Cronquist, B.; “The impact of software and CAE tools on SEU in field programmable gate arrays,” *IEEE Transactions on Nuclear Science*, Dec. 1999
- [2] Jih-Jong Wang; Katz, R.B.; Dhaoui, F.; McCollum, J.L.; Wong, W.; Cronquist, B.E.; Lambertson, R.T.; Hamdy, E.; Kleyner, I.; Parker, W.; “Clock buffer circuit soft errors in antifuse-based field programmable gate arrays,” *IEEE Transactions on Nuclear Science*, Dec. 2000
- [3] Wang, J.J.; Wong, W.; Wolday, S.; Cronquist, B.; McCollum, J.; Katz, R.; Kleyner, I.; “Single event upset and hardening in 0.15 μm antifuse-based field programmable gate array,” *IEEE Transactions on Nuclear Science*, Dec. 2003